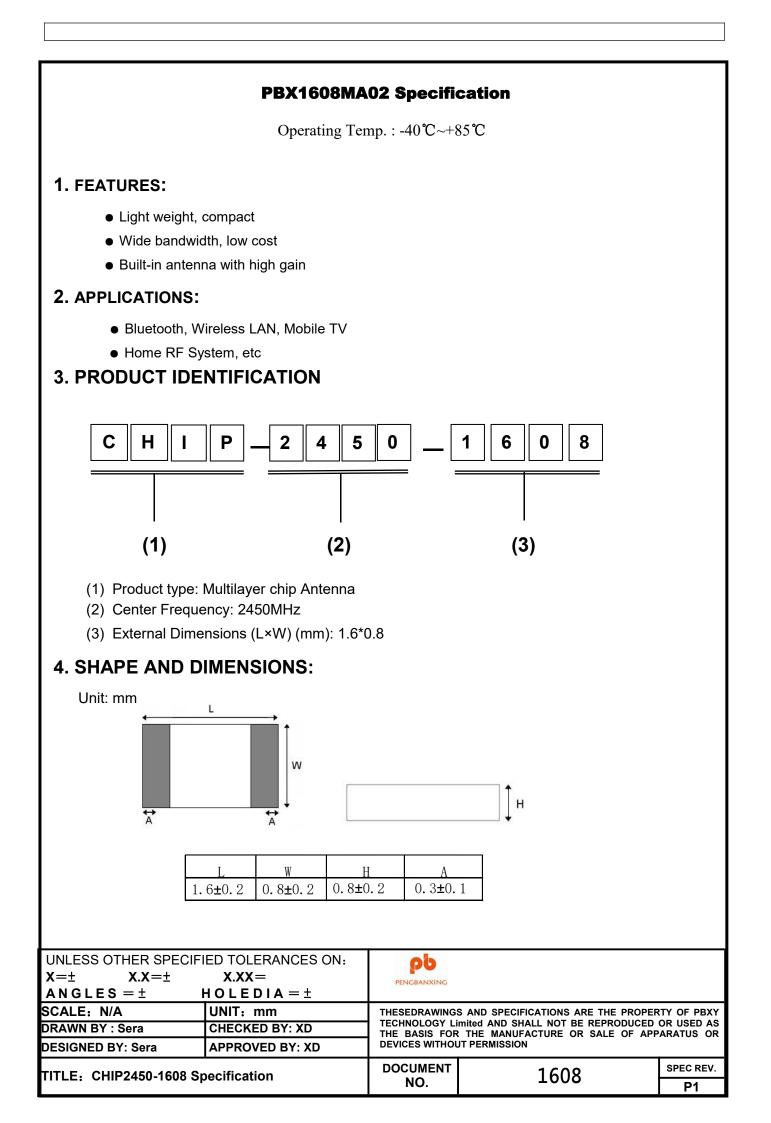
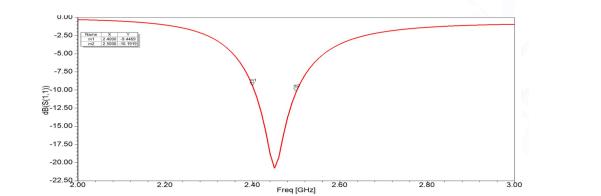
	产品规格承认书						
SPECIFICATIONS							
客户:							
CUSTOMER:							
产品名称:							
DESCRIPTIO	N:	<u>Chip antenna</u>					
客户型号:							
	ART NO:						
产品型号:		20					
OUR MODEL 」 日期:	NO:	<u> </u>	X1608MA	02			
DATE:			2021/09/01				
WITH YOUR .	APPROVED :	SIGNATUR	ES				
核准/ approval		审核/ check		制作/ make			
客	户/custon	ner					
	日期/Date						
UNLESS OTHER SPECIE $X=\pm$ X.X=± ANGLES = ±	FIED TOLERA X.XX= HOLEDIA		PENGBANXING	Address: 605, Park, Minzhi District, She	Building 4, 1970 Science Community, Minzhi Stree nzhen	e and Technology et, Longhua	
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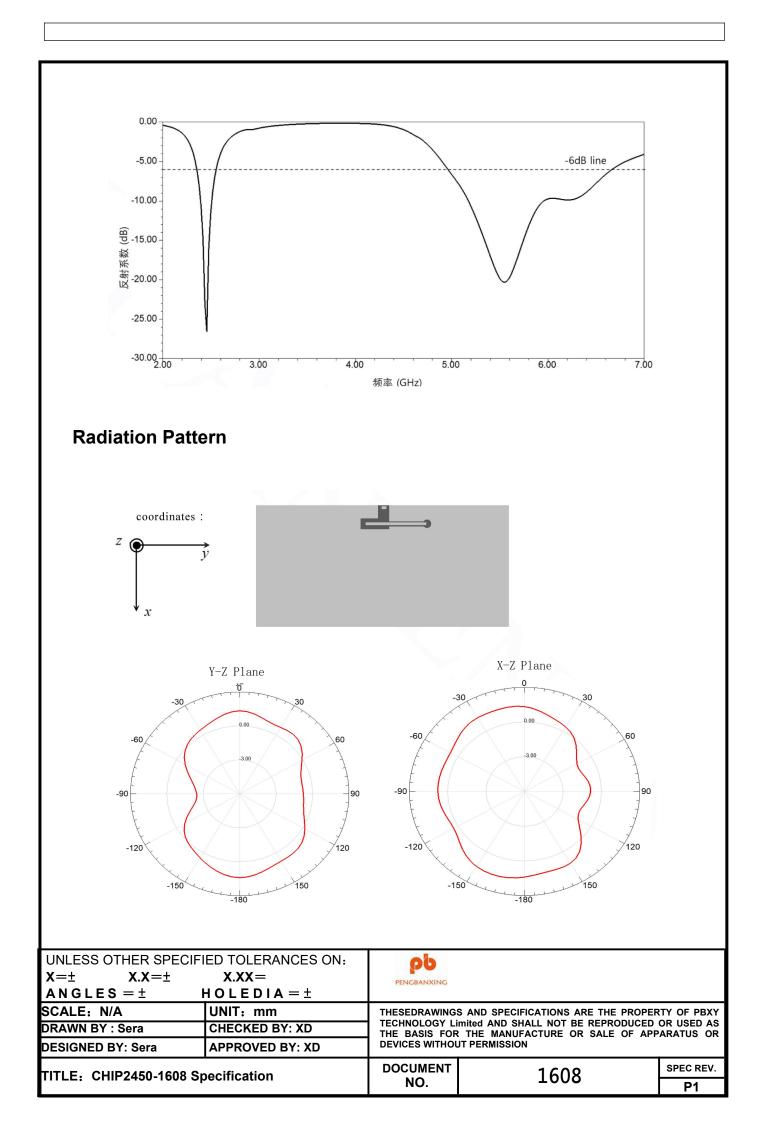


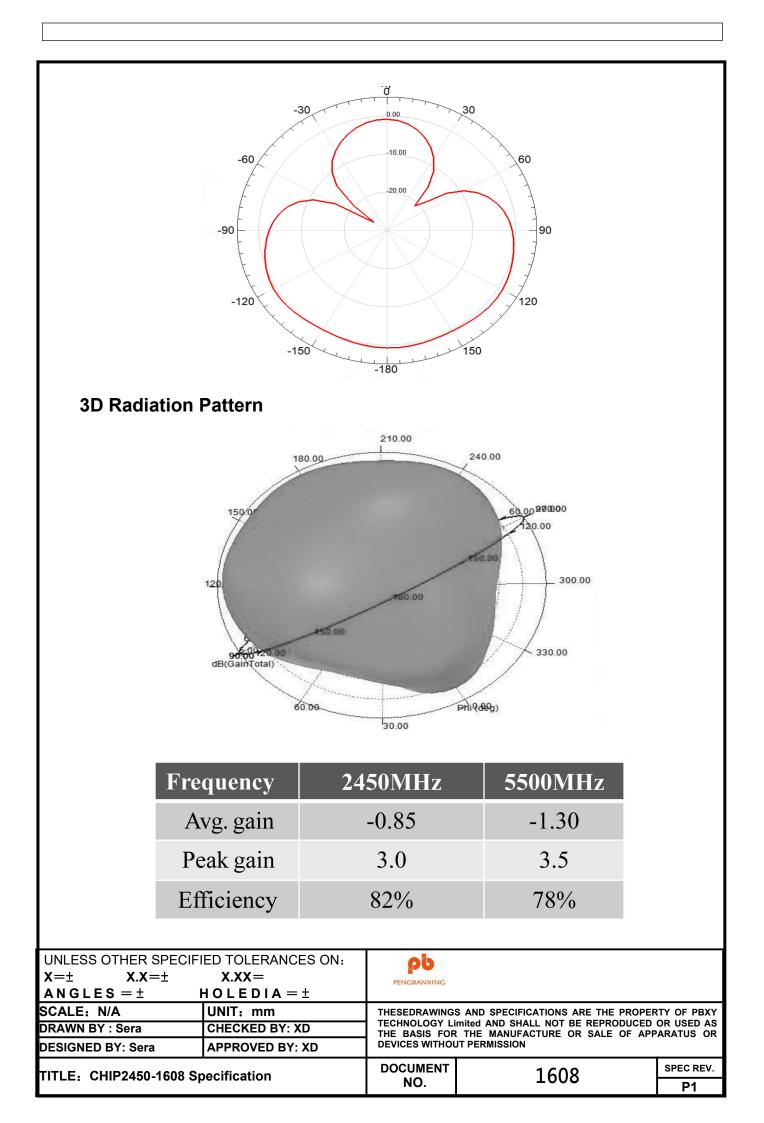
Electrical Characteristics Specification Feature 1 Central frequency 2.45GHz&5.5GHz 2 Bandwidth >100MHz 3 Peak gain 3.5dBi 4 VSWR <2 Polarization Linear 5 Azimuth beamwidth Omnidirectional 6 50 Ω 7 Impedance **Characteristic Curves** 90 80 70 11 1.80 70 2.00 50 100 110 120 130 50 140 40 150 30 160 20 0.21 m2 170 10 1.00 2.00 180 题 0 20 0.50 0 -20 -3r -10 -170 -160 -150 -40 -140 -110 -100 -90 -80 -70 -130 <Q.50

-120



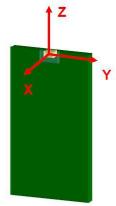
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DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION			
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.	
	Secification	NO. 1008		P1	

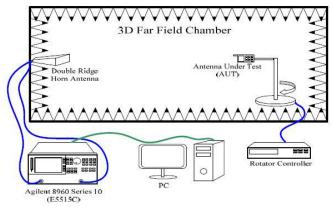




Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.





Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at -40° C $\pm5^{\circ}$ C, 2. Convert to $+105^{\circ}$ C (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ}$ C $\pm5^{\circ}$ C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}$ C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245 ± 5 °C for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40 $^\circ\!\mathrm{C}$ to +105 $^\circ\!\mathrm{C}$.

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SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBX		
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DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
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